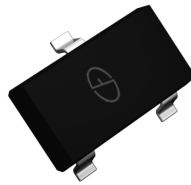
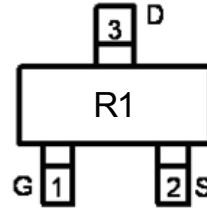


### Main Product Characteristics

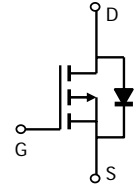
$V_{(BR)DSS}$	-30V
$R_{DS(on)MAX}$	60 mΩ@-10V
	70 mΩ@-4.5V
	85 mΩ@-2.5V
$I_D$	-4.2A



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Marking and Pin Assignment



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for DC-DC converter, power management in portable battery, computer, printer, cellular and general purpose applications
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The SSF3401A utilizes the latest processing techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in DC-DC converter, power management in portable battery, computer, printer, cellular and general purpose applications.

### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current	$I_D$	-4.2	A
Power Dissipation	$P_D$	400	mW
Thermal Resistance from Junction to Ambient ( $t < 5s$ )	$R_{\theta JA}$	313	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 to +150	$^\circ\text{C}$

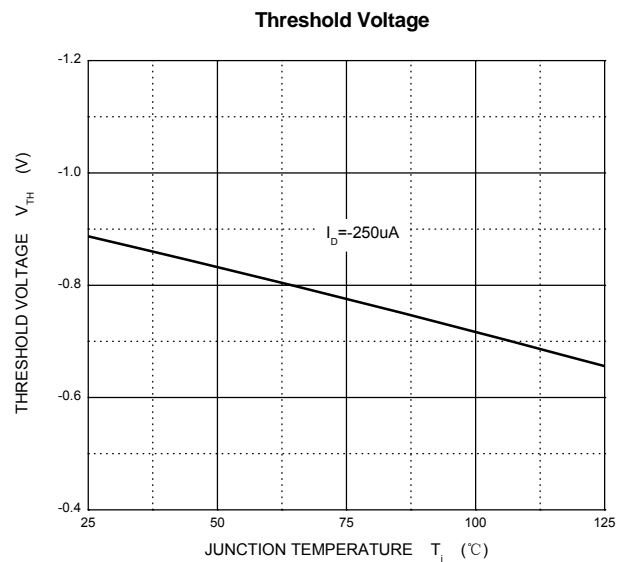
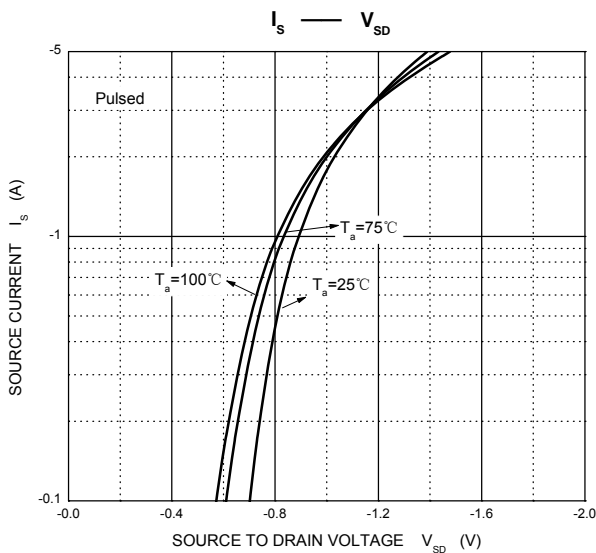
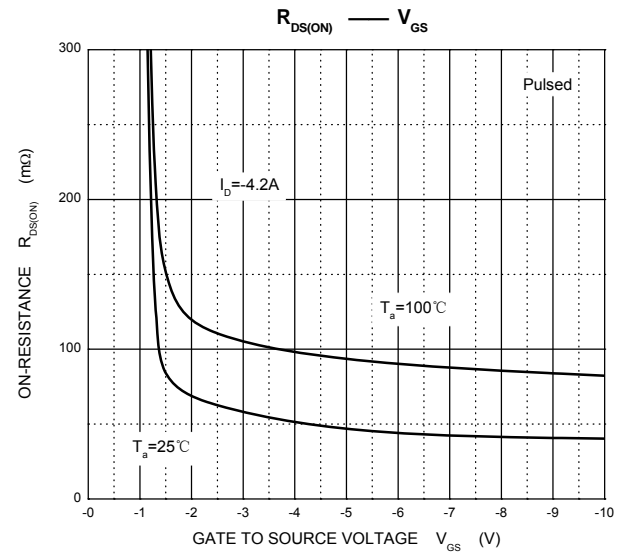
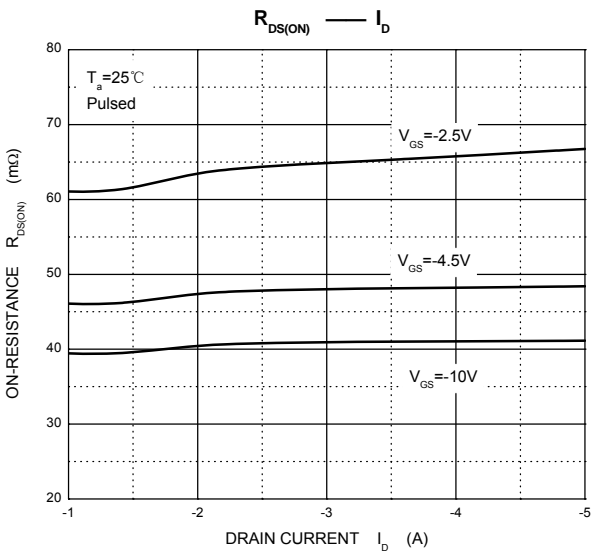
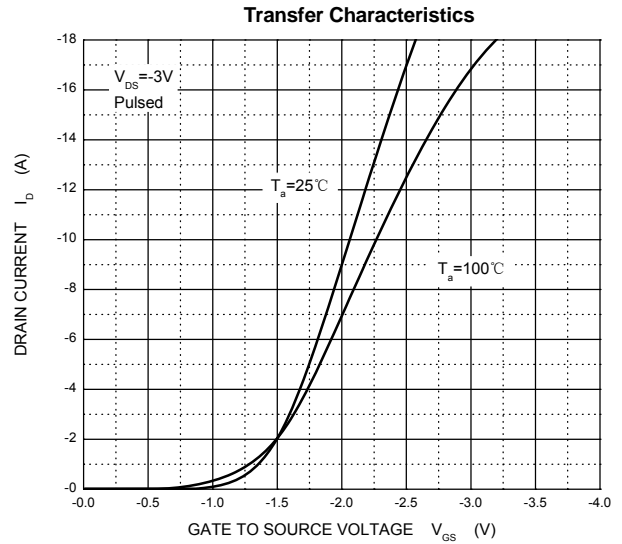
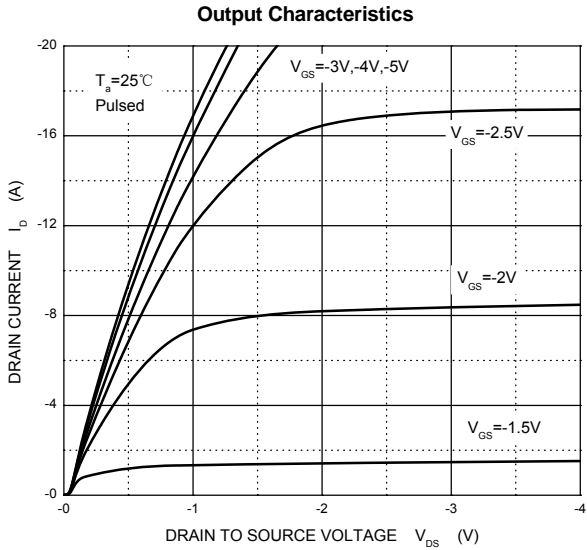
**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -24V, V_{GS} = 0V$			-1	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 12V, V_{DS} = 0V$			$\pm 100$	nA
<b>On Characteristics</b>						
Drain-Source On-Resistance (note 1)	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -4.2A$		41	60	m $\Omega$
		$V_{GS} = -4.5V, I_D = -4A$		47	70	m $\Omega$
		$V_{GS} = -2.5V, I_D = -1A$		61	85	m $\Omega$
Forward Transconductance (note 1)	$g_{FS}$	$V_{DS} = -5V, I_D = -5A$	7			S
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.7		-1.3	V
<b>Dynamic Characteristics (note 2)</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -15V, V_{GS} = 0V, f = 1MHz$		1050		pF
Output Capacitance	$C_{oss}$			127		pF
Reverse Transfer Capacitance	$C_{rss}$			85		pF
<b>Switching Characteristics (note 2)</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = -10V, V_{DS} = -15V,$ $R_L = 3.6\Omega, R_{GEN} = 6\Omega$			6.5	ns
Turn-On Rise Time	$t_r$				3.5	ns
Turn-Off Delay Time	$t_{d(off)}$				40	ns
Turn-Off Fall Time	$t_f$				13	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Diode Forward Voltage (note 1)	$V_{SD}$	$I_S = -1A, V_{GS} = 0V$			-1	V

**Note :**

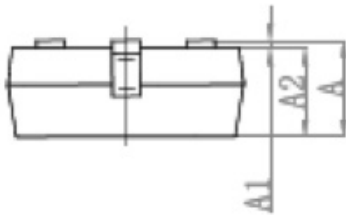
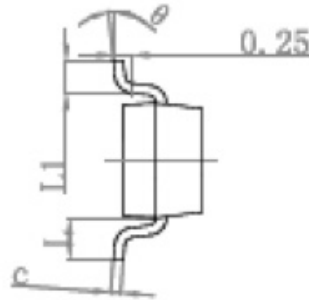
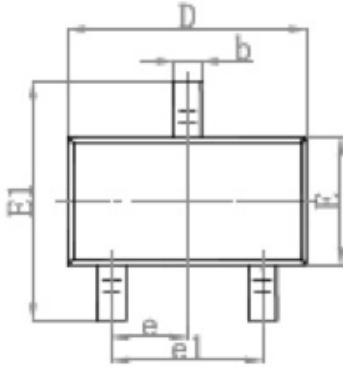
1. Pulse Test : Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
2. These parameters have no way to verify.

**Typical Electrical and Thermal Characteristics**



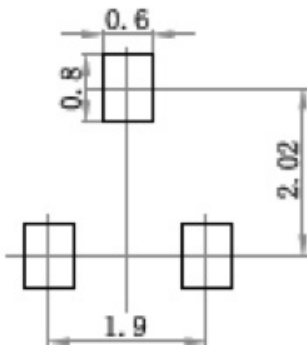
## Package Outline Dimensions

SOT-23



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

## Suggested Pad Layout



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$ .
3. The pad layout is for reference purposes only.